

30V N-Channel Enhancement Mode Power MOSFET

Description

EMR12N03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

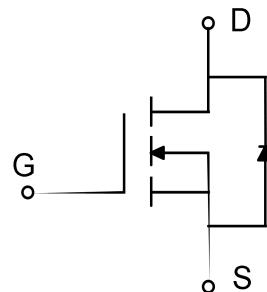
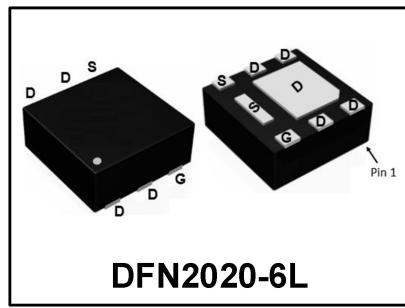
Features

- $V_{DS} = 30V$, $I_D = 12A$
 - $R_{DS(on)} < 9m\Omega$ @ $V_{GS} = 10V$
 - $R_{DS(on)} < 12.5m\Omega$ @ $V_{GS} = 4.5V$
- Green Device Available
- High Power and Current Handling Capability

Applications

- Battery Protection
- Power Management
- Load Switch

Schematic



Absolute Maximum Ratings

| Parameter | | Symbol | Value | Unit |
|--|-------------------|----------------|------------|------|
| Drain-Source Voltage | | V_{DS} | 30 | V |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| Continuous Drain Current | $T_A=25^\circ C$ | I_D | 12 | A |
| | $T_A=100^\circ C$ | | 7 | |
| Pulsed Drain Current ⁴ | | I_{DM} | 48 | A |
| Single Pulse Avalanche Energy ³ | | E_{AS} | 20 | mJ |
| Total Power Dissipation | $T_A=25^\circ C$ | P_D | 2.1 | W |
| Operating Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|------|
| Thermal Resistance from Junction-to-Ambient ¹ | $R_{\theta JA}$ | 60 | °C/W |

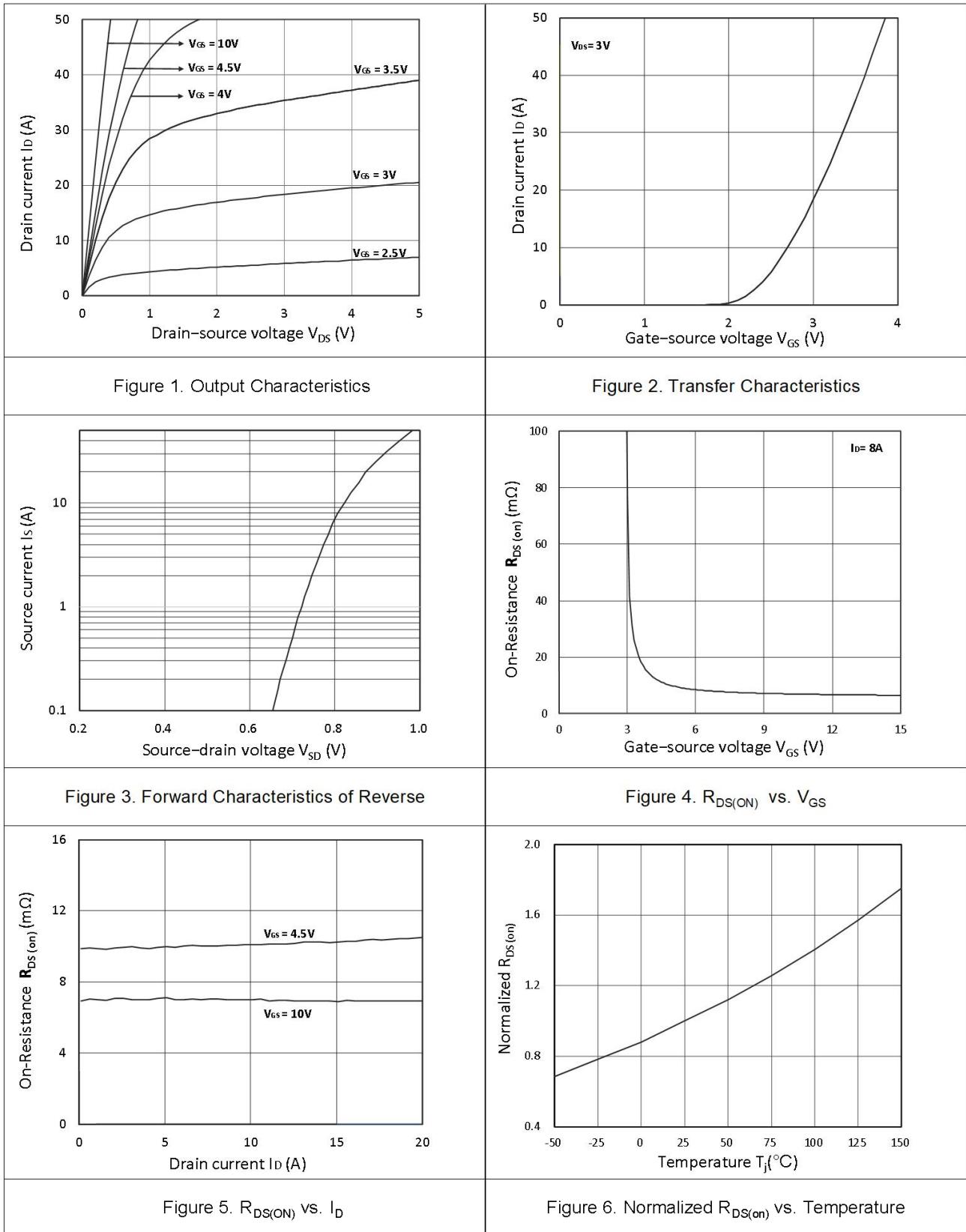
Electrical Characteristics $T_c = 25^\circ C$, unless otherwise noted

| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|--|---------------|---|------|------|-----------|-----------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 30 | - | - | V |
| Gate-body Leakage current | I_{GSS} | $V_{DS} = 0V, V_{GS} = \pm 20V$ | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DS} | $V_{DS} = 30V, V_{GS} = 0V$ | - | - | 1 | μA |
| Gate-Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1 | 1.6 | 2.5 | V |
| Drain-Source on-Resistance ² | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 8A$ | - | 6.8 | 9 | $m\Omega$ |
| | | $V_{GS} = 4.5V, I_D = 6A$ | - | 10 | 12.5 | |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 15V, V_{GS} = 0V, f = 1.0 \text{ MHz}$ | - | 1250 | - | pF |
| Output Capacitance | C_{oss} | | - | 174 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 142 | - | |
| Switching Characteristics | | | | | | |
| Gate Resistance | R_G | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$ | - | 2.8 | - | Ω |
| Total Gate Charge | Q_g | $V_{GS} = 4.5V, V_{DS} = 15V, I_D = 12A$ | - | 10 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 3.5 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 2.2 | - | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{GS} = 4.5V, V_{DS} = 15V, I_D = 10A, R_G = 3\Omega$ | - | 8 | - | ns |
| Rise Time | t_r | | - | 28 | - | |
| Turn-off Delay Time | $t_{d(off)}$ | | - | 15 | - | |
| Fall Time | t_f | | - | 7 | - | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Diode Forward Voltage ² | V_{SD} | $I_S = 1A, V_{GS} = 0V$ | - | - | 1.2 | V |
| Continuous Source Current ^{1,5} | I_S | $V_G = V_D = 0V, \text{Force Current}$ | - | - | 12 | A |

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 20A$
4. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ C$.
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

Typical Characteristics



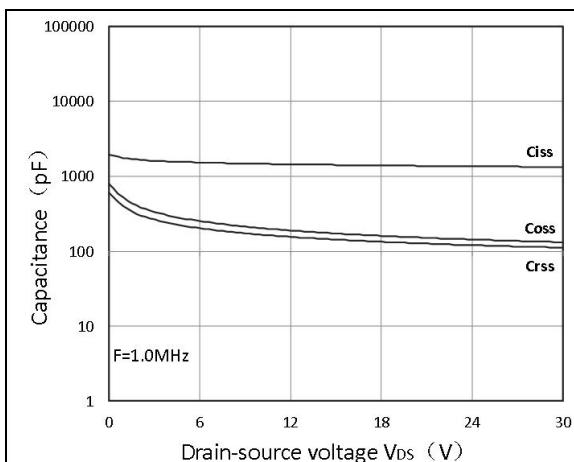


Figure 7. Capacitance Characteristics

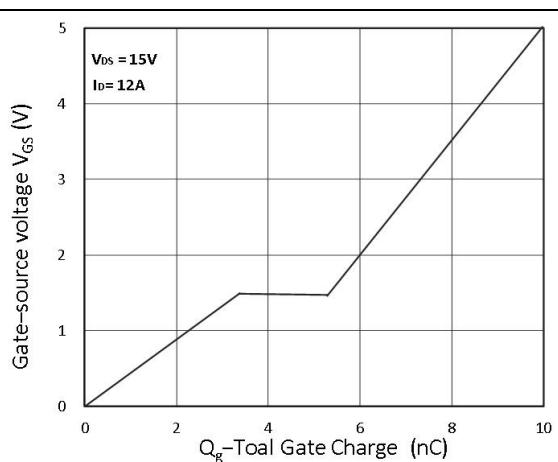


Figure 8. Gate Charge Characteristics

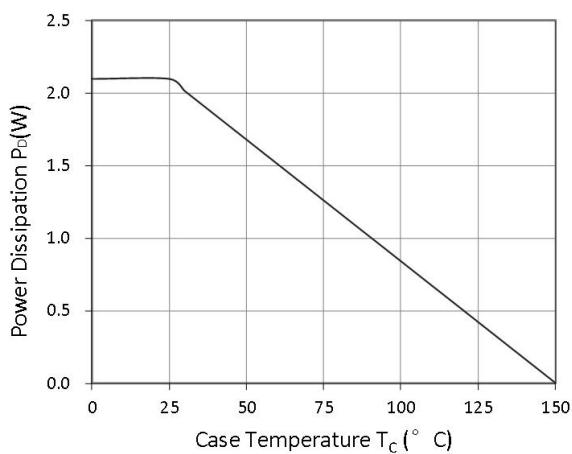


Figure 9. Power Dissipation

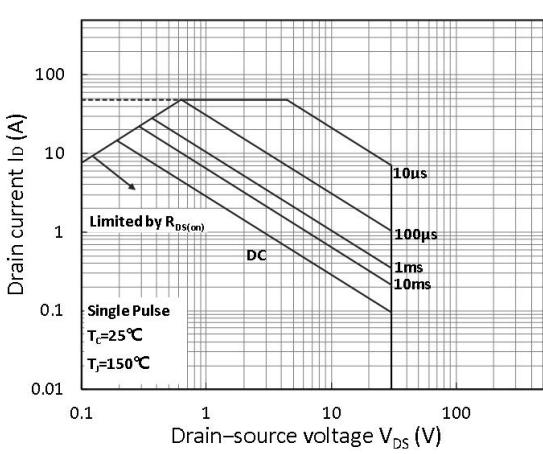


Figure 10. Safe Operating Area

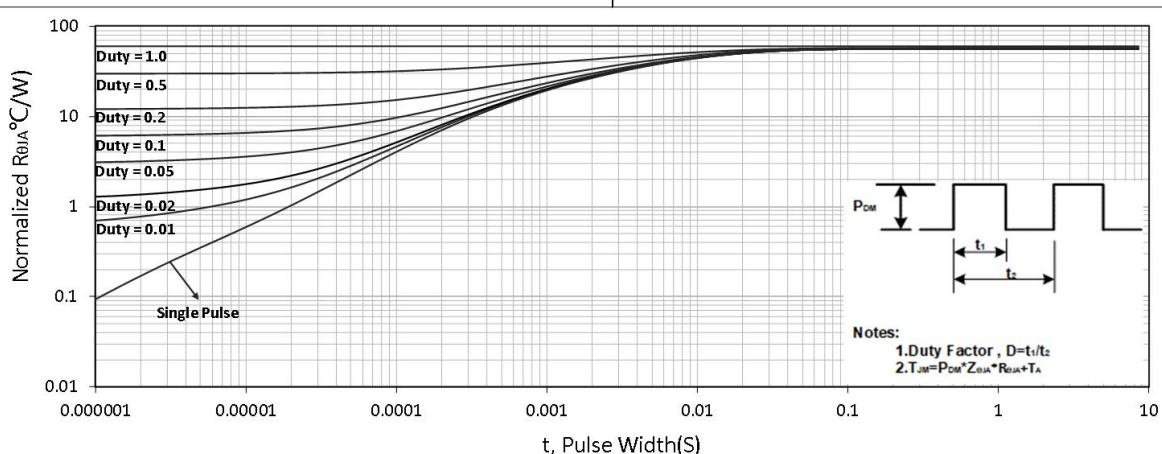


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

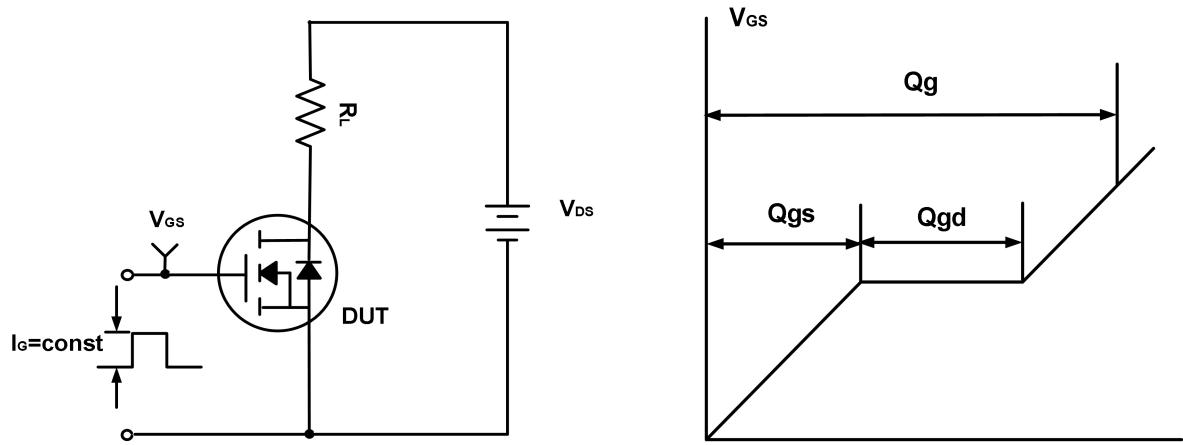


Figure A. Gate Charge Test Circuit & Waveforms

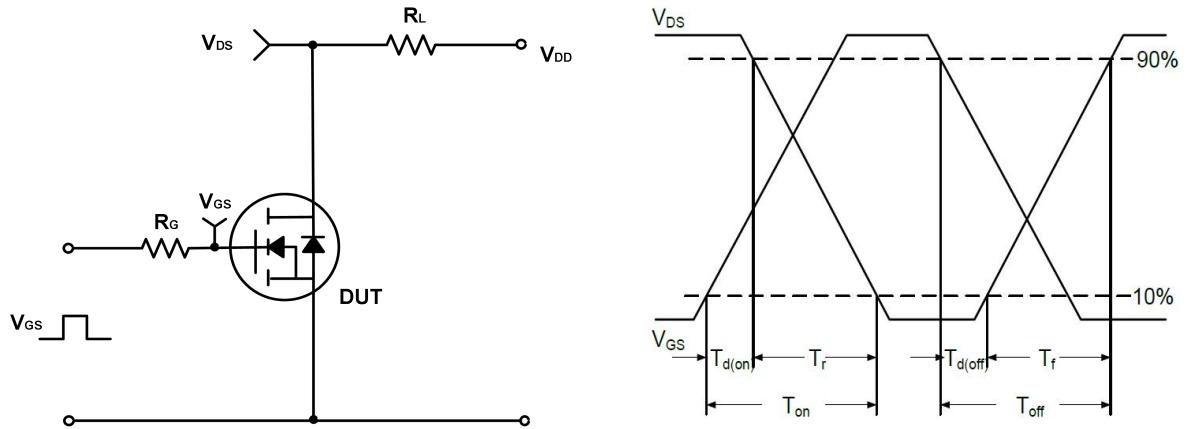


Figure B. Switching Test Circuit & Waveforms

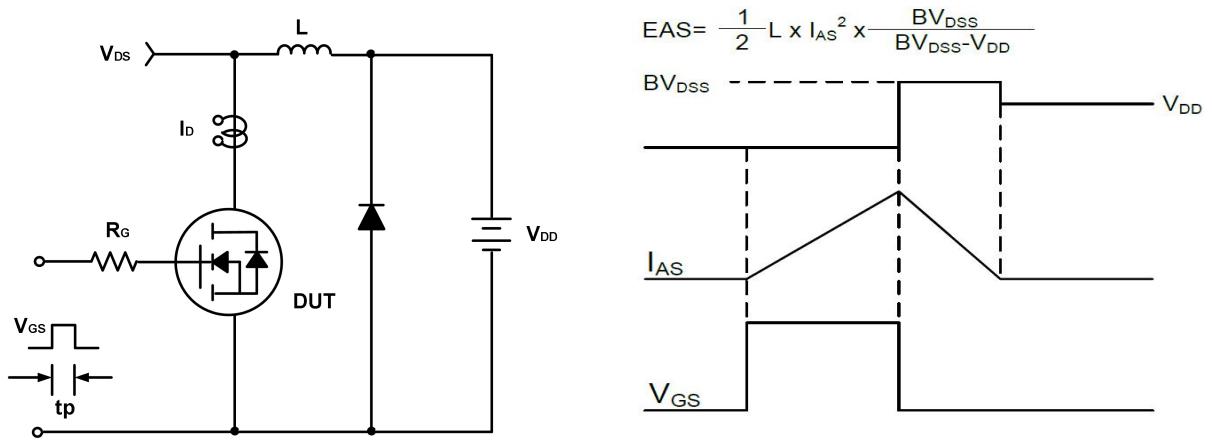
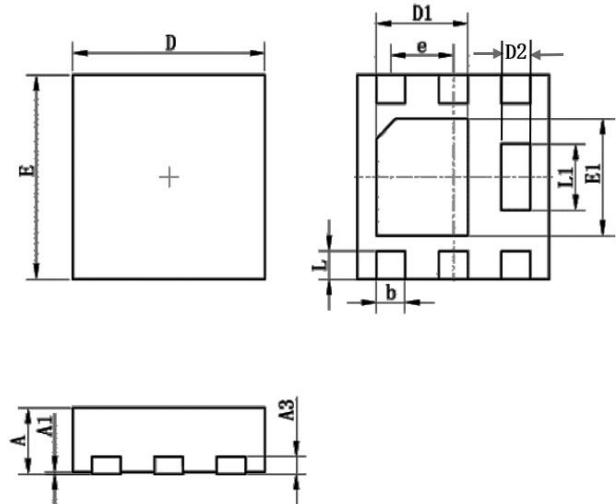
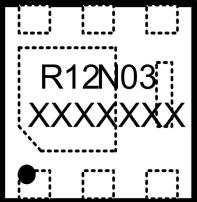


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Mechanical Dimensions for DFN2020-6L

| SYMBOL | MM | |
|--------|----------|------|
| | MIN | MAX |
| A | 0.50 | 0.60 |
| A1 | 0.00 | 0.05 |
| A3 | 0.152REF | |
| b | 0.25 | 0.35 |
| D | 1.90 | 2.10 |
| D1 | 0.80 | 1.00 |
| E | 1.90 | 2.10 |
| E1 | 0.80 | 1.00 |
| L1 | 0.46 | 0.66 |
| D2 | 0.25 | 0.35 |
| e | 0.65BSC | |
| L | 0.25 | 0.35 |

PACKAGE OUTLINE**Marking Information**

| Part No. | Marking |
|------------|---|
| EMR12N03T1 |  <p>R12N03= Device code XXXXXXX= Date code</p> |

Revision History

| No. | Version | Date | Revision Item | Request | Function and characteristic checking | Package dimension checking | Typos checking |
|-----|---------|------------|------------------|------------|--------------------------------------|----------------------------|----------------|
| 1 | 1.0 | 2020-05-08 | Released Version | Qi Shu Kun | Qi Shu Kun | Liu Jia Ying | Liu Jia Ying |
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